1-1658438-5 ACTIVE

MICTOR

TE Internal #: 1-1658438-5

PCB Mount Header, Vertical, Board-to-Board, 140 Position, .8 mm [.

031 in] Centerline, Fully Shrouded, Gold Flash, Surface Mount,

Power & Signal, Black

View on TE.com >



Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 140

Centerline (Pitch): .8 mm [.031 in]

Features

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Fully Shrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Stackable	No

Differential Load

PCB Mount Orientation Vertical

Number of Positions 140

Board-to-Board Configuration Parallel

Electrical Characteristics

Connector Contact Load Condition

Dielectric Withstanding Voltage (Max)	675 VAC
Insulation Resistance	2 ΜΩ



Operating Voltage Body Features Primary Product Color Black Contact Features PCB Contact Lermination Area Plating Material Thickness 25 µm [9.8425 µm] Mating Lao Thickness 25 µm [9.8425 µm] Mating Lao Thickness 25 µm [9.8425 µm] Contact Shape & Form Single Beam, Square PCB Contact Termination Area Plating Material Contact Beew Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Type Pin Contact Current Rating (Max) Termination Features Rectangular Termination Post & Tall Midth Permination Method to Printed Circuit Board Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention Mating Retention Mating Retention Mating Retention With Mating Alignment PCB Mount Alignment PCB Mount Alignment PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Contacting (Pitch) 8 mm [031 in] LCP (Liquid Crystal Polymen) Dimensions Connector Height 13.39 mm [526 in] Stack Height 4 mm [551 in]	Impedance	100 Ω
Primary Product Color Contact Features PCB Contact Termination Area Plating Material Thickness	Operating Voltage	125 VAC
Contact Features PCB Contact Termination Area Plating Material Thickness .25 µm 9.8425 µm Mating Tab Wridth .38 nm .015 im Mating Tab Thickness .2 mm .008 im Contact Shape & horm .5 mgle Beam, Square PCB Contact Termination Area Plating Material .6 Gold .6 Contact Base Material .7 Phosphor Bronze .7 Contact Mating Area Plating Material .7 Expansion .25 µm 9.8425 µm Contact Mating Area Plating Material .7 Expansion .25 µm 9.8425 µm Contact Type .7 Pin .7 Contact Current Rating (Max) .1.25 A, 9.5 A .7 Expansion Features Rectangular Termination Post & Tail Thickness .2 rmm .008 im Rectangular Termination Post & Tail Thickness .2 rmm .008 im Rectangular Termination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im Rectangular Lermination Post & Tail Thickness .2 rmm .008 im .008 im Rectangular Lermination Post &	Body Features	
PCB Contact Termination Area Plating Material Thickness	Primary Product Color	Black
Mating Tab Width	Contact Features	
Mating Tab Thickness	PCB Contact Termination Area Plating Material Thickness	.25 µm[9.8425 µin]
Contact Shape & Form PCB Contact Termination Area Plating Material Contact Base Material Contact Mating Area Plating Material Contact Mating Area Plating Material Contact Mating Area Plating Material Thickness Contact Type Pin Contact Current Rating (Max) 1.25 A, 9.5 A Termination Features Rectangular Termination Post & Tail Thickness Rectangular Termination Post & Tail Width 9 mm[.035 in] Termination Method to Printed Circuit Board Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment With PCB Mount Alignment With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Mating Tab Width	.38 mm[.015 in]
PCB Contact Termination Area Plating Material Contact Base Material Phosphor Bronze Contact Mating Area Plating Material Contact Mating Area Plating Material Thickness 25 µm[9.8425 µm] Contact Type Pin Contact Current Rating (Max) 1.25 A, 9.5 A Termination Features Rectangular Termination Post & Tail Thickness 2 mm[.008 in] Rectangular Termination Post & Tail Width 9 mm[.035 in] Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment PCB Mount Alignment Type locating Posts Mating Retention With Mating Alignment Without PCB Mount Alignment With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 8 mm[.031 in] Housing Material Dimensions Connector Height 13.39 mm[.526 in]	Mating Tab Thickness	.2 mm[.008 in]
Contact Base Material Phosphor Bronze Contact Mating Area Plating Material Gold Flash Contact Mating Area Plating Material Thickness 25 µm[9.8425 µin] Contact Type Pin Contact Current Rating (Max) 1.25 A, 9.5 A Termination Features Rectangular Termination Post & Tail Thickness 2 mm[.008 in] Rectangular Termination Post & Tail Width 9 mm[.035 in] Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment Without PCB Mount Alignment PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Ptch) 8 mm[.031 in] Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Contact Shape & Form	Single Beam, Square
Contact Mating Area Plating Material Contact Mating Area Plating Material Thickness Contact Type Pin Contact Current Rating (Max) 1.25 A, 9.5 A Termination Features Rectangular Termination Post & Tail Thickness Rectangular Termination Post & Tail Width 9 mm[.035 in] Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment PCB Mount Retention With PCB Mount Retention With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Remination (Pi	PCB Contact Termination Area Plating Material	Gold
Contact Mating Area Plating Material Thickness Contact Type Pin Contact Current Rating (Max) 1.25 A, 9.5 A Termination Features Rectangular Termination Post & Tail Thickness Rectangular Termination Post & Tail Width 9 mm[.008 in] Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Reminosions Connector Height 13.39 mm[.526 in]	Contact Base Material	Phosphor Bronze
Contact Type Contact Current Rating (Max) 1.25 A, 9.5 A Termination Features Rectangular Termination Post & Tail Thickness Rectangular Termination Post & Tail Width .9 mm[.035 in] Termination Method to Printed Circuit Board Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment Without PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Reminions Connector Height 13.39 mm[.526 in]	Contact Mating Area Plating Material	Gold Flash
Contact Current Rating (Max) Termination Features Rectangular Termination Post & Tail Thickness Rectangular Termination Post & Tail Width Rectangular Termination Post & Tail Width Permination Method to Printed Circuit Board Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment Without PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 rmm[.526 in]	Contact Mating Area Plating Material Thickness	.25 μm[9.8425 μin]
Termination Features Rectangular Termination Post & Tail Thickness .2 mm[.008 in] Rectangular Termination Post & Tail Width .9 mm[.035 in] Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment Without PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) .8 mm[.031 in] Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Contact Type	Pin
Rectangular Termination Post & Tail Thickness Rectangular Termination Post & Tail Width .9 mm[.035 in] Termination Method to Printed Circuit Board Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Board Mount LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Contact Current Rating (Max)	1.25 A, 9.5 A
Rectangular Termination Post & Tail Width .9 mm[.035 in] Termination Method to Printed Circuit Board Surface Mount Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment Without PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) .8 mm[.031 in] Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Termination Features	
Termination Method to Printed Circuit Board Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment Without PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Mechanical Attachment PCB Mount Alignment Type Locating Posts Mating Retention With Mating Alignment Without PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) 8 mm[.031 in] Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Rectangular Termination Post & Tail Width	.9 mm[.035 in]
PCB Mount Alignment Type Mating Retention With Mating Alignment PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Termination Method to Printed Circuit Board	Surface Mount
Mating Retention With Mating Alignment Without PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Board Mount LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Mechanical Attachment	
Mating Alignment PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Board Mount LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	PCB Mount Alignment Type	Locating Posts
PCB Mount Retention With PCB Mount Alignment With Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Board Mount LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Mating Retention	With
PCB Mount Alignment Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Board Mount LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Mating Alignment	Without
Connector Mounting Type Board Mount Housing Features Centerline (Pitch) Board Mount LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	PCB Mount Retention	With
Housing Features Centerline (Pitch) Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	PCB Mount Alignment	With
Centerline (Pitch) Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Connector Mounting Type	Board Mount
Housing Material LCP (Liquid Crystal Polymer) Dimensions Connector Height 13.39 mm[.526 in]	Housing Features	
Dimensions Connector Height 13.39 mm[.526 in]	Centerline (Pitch)	.8 mm[.031 in]
Connector Height 13.39 mm[.526 in]	Housing Material	LCP (Liquid Crystal Polymer)
	Dimensions	
Stack Height 14 mm[.551 in]	Connector Height	13.39 mm[.526 in]
	Stack Height	14 mm[.551 in]



PCB Thickness (Recommended)	.06 mm[.25 in]
Usage Conditions	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Assembly Process Feature	None
Circuit Application	Power & Signal
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	20
Packaging Type	Box, Tray

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



Compatible Parts

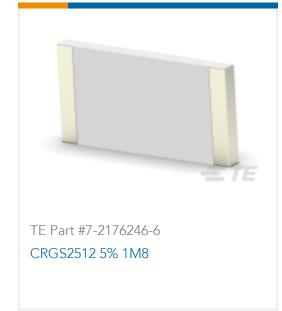


Customers Also Bought















Documents

Product Drawings

MSB0.80PL14ASY140DP,-,10,VCTY

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_1-1658438-5_J.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_1-1658438-5_J.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_1-1658438-5_J.3d_stp.zip

PCB Mount Header, Vertical, Board-to-Board, 140 Position, .8 mm [.031 in] Centerline, Fully Shrouded, Gold Flash, Surface Mount, Power & Signal, Black



English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English